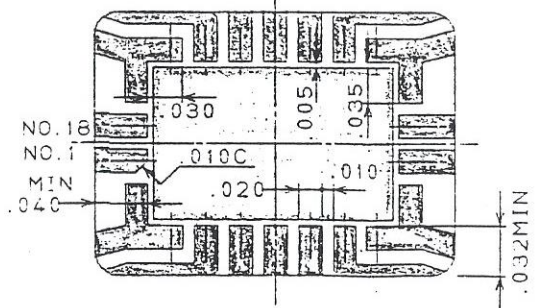
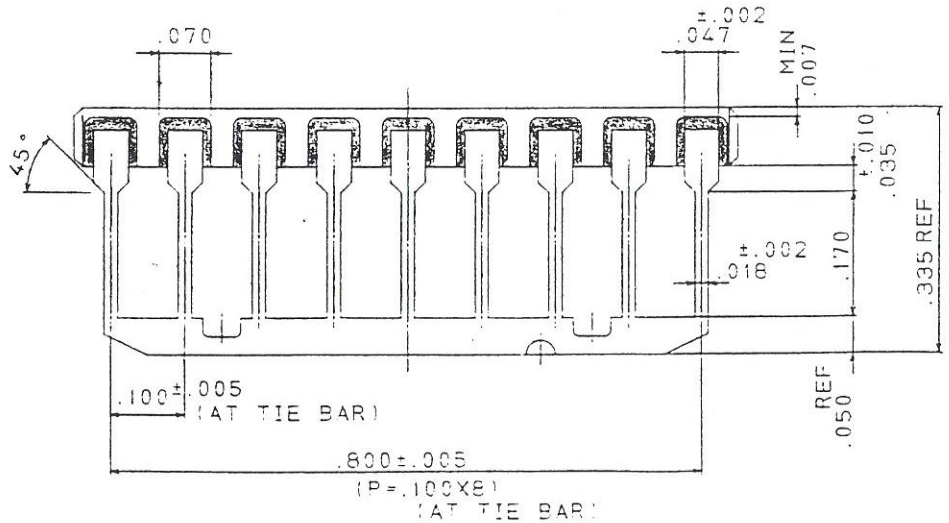


NOTE:

1. SHALL APPLY.
2. NI (100# MIN)
+GOLD (60# MIN)
3. NO LEAD TO BE ELECTRICALLY CONNECTED TO THE DIE ATTACH PAD. SEAL RING ISOLATED
4. D/A Pad FLATNESS 1.35 MIL MAX



DETAIL BONDING PADS

2	LEAD	ALLOY42	
1	CERAMIC	BLACK ALUMINA	
Item	Name	Material	Description
UNLESS OTHERWISE SPECIFIED TOLERANCES		DRAWN H. KONDO	
± 1% 2 DECIMALS .XX ± .01		CHECKED	
N. L. T. 3 DECIMALS .XXX ± .025		APPROVED <i>J. Gai</i>	
		UNIT INCH	DWG NO.
		SCALE 5/1	18LD S/B PACKAGE
			DWG NO. 18LD S/B PACKAGE
			STP
			AT

